



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2826

Applicant: Taylor R. Efland

Docket: TI-31678

Serial No.: 09/975,630

Art Unit: 2826

Filed: 10/12/01

Examiner: Andujar, L.

For: Circuit Structure Integrating the Power Distribution Functions of Circuits and Leadframes into the Chip Surface

SUPPLEMENT TO AMENDMENT FILED UNDER 35 U.S.C. 111

February 24, 2003

Assistant Commissioner For Patents  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that on this date the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.

*Michael K. Skrehot*  
Michael K. Skrehot, Reg. No. 36,682

*2-24-03*  
Date

Dear Sir:

Applicant inadvertently omitted the proposed drawings from the enveloped mailed even date herewith containing a response to the Office Action mailed 10/24/02. The drawings are attached. Charge any and all fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

*Michael K. Skrehot*

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